



## Product Change Notification: CAAN-120SGH090

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**Date:**

16-Jun-2026

**Product Category:**

32-Bit Microprocessors

**Notification Subject:**

CCB 7410 Final Notice: Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

**Affected CPNs:**

[CAAN-120SGH090\\_Affected\\_CPN\\_06162026.pdf](#)

[CAAN-120SGH090\\_Affected\\_CPN\\_06162026.csv](#)

**PCN Status:** Final Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

**Pre and Post Summary Changes:**

|               | Pre Change                             | Post Change                            |                                      | Change<br>(Yes/No) |
|---------------|----------------------------------------|----------------------------------------|--------------------------------------|--------------------|
| Assembly Site | ATX<br>Semiconductor<br>(Shanghai) Co. | ATX<br>Semiconductor<br>(Shanghai) Co. | ASE<br>Group -<br>Malaysia<br>(ASEM) | Yes                |

|                                  | Ltd<br>(ASSH)   | Ltd<br>(ASSH)   |                       |     |
|----------------------------------|-----------------|-----------------|-----------------------|-----|
| <b>Wire Material</b>             | Au              | Au              | Au                    | No  |
| <b>Die Attach Material</b>       | 2100AS          | 2100AS          | ABL2100<br>A          | Yes |
| <b>Molding Compound Material</b> | KE-G1250        | KE-G1250        | KEG<br>1250LKDS<br>-C | Yes |
| <b>Core Material</b>             | CCL-<br>HL832NX | CCL-<br>HL832NX | CCL-<br>HL832NX       | No  |
| <b>Substrate Material</b>        | AUS308          | AUS308          | AUS308                | No  |

**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve on-time delivery performance by qualifying ASEM as an additional assembly site.

**Change Implementation Status:** In Progress

**Estimated First Ship Date:** 10 July 2026 (date code: 2628)

**Note Below EFSD:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

|                                      | <b>February 2025</b> |    |    |    |    | > | <b>June 2026</b> |    |    |    |    | <b>July 2026</b> |    |    |    |
|--------------------------------------|----------------------|----|----|----|----|---|------------------|----|----|----|----|------------------|----|----|----|
| <b>Work Week</b>                     | 05                   | 06 | 07 | 08 | 09 |   | 23               | 24 | 25 | 26 | 27 | 28               | 29 | 30 | 31 |
| <b>Initial PCN Issue Date</b>        |                      |    |    | X  |    |   |                  |    |    |    |    |                  |    |    |    |
| <b>Qual Report Availability</b>      |                      |    |    |    |    |   |                  |    | X  |    |    |                  |    |    |    |
| <b>Final PCN Issue Date</b>          |                      |    |    |    |    |   |                  |    | X  |    |    |                  |    |    |    |
| <b>Estimated Implementation Date</b> |                      |    |    |    |    |   |                  |    |    |    |    | X                |    |    |    |

**Method to Identify Change:** Traceability Code

**Qualification Report:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Report.

**Revision History:** February 18, 2025: Issued initial notification  
June 16, 2026: Issued final notification. Attached the qualification report. Added column "Change (Yes/No)" in the pre and post change table. Provided estimated first ship date to be on July 10, 2026.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**PCN CAAN-120SGH090 Qual Report.pdf**

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

**Terms and Conditions:**

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If you wish to [change your PCN profile, including opt out,](#) please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

AT91SAM9260B-CU

AT91SAM9260B-CU-999



**QUALIFICATION REPORT SUMMARY**  
RELIABILITY LABORATORY

**PCN #: CAAN-12OSGH090**

**Date:**  
**June 08, 2026**

**Qualification of ASEM as an additional assembly site for  
AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part  
numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.**



## MICROCHIP Package Qualification Report

**Purpose:** Qualification of ASEM as an additional assembly site for AT91SAM9260B-CU and AT91SAM9260B-CU-999 catalog part numbers (CPN) available in 217L LFBGA (15x15x1.4mm) package.

**CCB No.:** 7410

|                   |                                          |                  |
|-------------------|------------------------------------------|------------------|
| <b>Misc.</b>      | Assembly site                            | ASEM             |
|                   | BD Number                                | BD-002991 rev 02 |
|                   | MP Code (MPC)                            | 58A937ATBC02     |
|                   | Part Number (CPN)                        | AT91SAM9260B-CU  |
|                   | MSL information                          | MSL3/260         |
|                   | Assembly Shipping Media (T/R, Tube/Tray) | TRAY             |
|                   | Base Quantity Multiple (BQM)             | 126              |
| <b>Substrate</b>  | Core Material                            | CCL-HL832NX      |
|                   | Core Thickness                           | 250+/-30 UM      |
|                   | L1/L2 Thickness                          | 18 UM MIN        |
|                   | SM Material                              | Aus308           |
|                   | Process                                  | STD              |
|                   | SM Thickness                             | 30+/-10 UM       |
|                   | Part Number                              | 14ABS7012456XLM  |
|                   | Drill Size                               | 150+/-25 UM      |
|                   | Line/Space Specs                         | 30/30 UM MIN     |
| <b>Bond Wire</b>  | Material                                 | Au               |
| <b>Die Attach</b> | Part Number                              | ABL2100A         |
|                   | Conductive                               | Yes              |
| <b>MC</b>         | Part Number                              | KEG 1250LKDS-C   |
| <b>PKG</b>        | PKG Type                                 | LFBGA            |
|                   | Pin/Ball Count                           | 217              |
|                   | PKG width/size                           | 15x15x1.4 mm     |
|                   | Solder Ball Material                     | SAC105           |



## **MICROCHIP**

### **Package Qualification Report**

#### **Manufacturing Information:**

| <b>Assembly Lot No.</b> |
|-------------------------|
| ASEM255200019.000       |
| ASEM255200020.000       |
| ASEM255200021.000       |

**Result:**

☒

Pass

☐

Fail

☐

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Qualification of 58A93 AT91SAM9260B-CU Au 0.9mil wire in 217L LFBGA 15x15x1.4mm (ATB) at ASEM is qualified for MSL 3 at 260°C as per JESD22A113 and is Passed in accordance to QCI-39000.



## MICROCHIP

### Package Qualification Report

#### Moisture Soak Precondition Prior to Stresses

|                                        |                                                                                               |       |       |
|----------------------------------------|-----------------------------------------------------------------------------------------------|-------|-------|
| Test Method                            | JESD22-A113; IPC/JEDEC J-STD-020                                                              |       |       |
| Test Condition                         | <b>MSL 3:</b> 150C 24-hour Bake. 192-hour moisture soak at 30°C/60RH. 3x Reflow at 260°C max. |       |       |
| Required Sample Size                   | 231 each lot / 3 lots                                                                         |       |       |
| Electrical Test at +85°C (Fail / Pass) | 0/300                                                                                         | 0/300 | 0/300 |
| Result                                 | Pass                                                                                          |       |       |

#### High Temp Storage

|                                        |                          |  |  |
|----------------------------------------|--------------------------|--|--|
| Test Method                            | JESD22-A103              |  |  |
| Test Condition                         | 150°C / <b>504</b> hours |  |  |
| Required Sample Size                   | 45 units / 1 Lot         |  |  |
| Electrical Test at +85°C (Fail / Pass) | 0/60                     |  |  |
| Result                                 | Pass                     |  |  |

|                                        |                           |  |  |
|----------------------------------------|---------------------------|--|--|
| Test Condition                         | 150°C / <b>1008</b> hours |  |  |
| Required Sample Size                   | 45 units / 1 Lot          |  |  |
| Electrical Test at +85°C (Fail / Pass) | 0/60                      |  |  |
| Result                                 | Pass                      |  |  |

#### Temperature Cycling

|                                        |                                               |      |      |
|----------------------------------------|-----------------------------------------------|------|------|
| Test Method                            | JESD22-A104                                   |      |      |
| Test Condition                         | -55°C / 125°C Air to Air / <b>1000</b> Cycles |      |      |
| Required Sample Size                   | 77 each lot / 3 lots                          |      |      |
| Electrical Test at +85°C (Fail / Pass) | 0/90                                          | 0/90 | 0/90 |
| WBP/WBS (Fail/Pass)                    | Pass                                          | Pass | Pass |
| Overall Result                         | Pass                                          |      |      |

#### Unbiased HAST

|                                        |                                    |      |      |
|----------------------------------------|------------------------------------|------|------|
| Test Method                            | JESD22-A18                         |      |      |
| Test Condition                         | +110°C / 85% RH / <b>264</b> hours |      |      |
| Required Sample Size                   | 77 each lot / 3 lots               |      |      |
| Electrical Test at +85°C (Fail / Pass) | 0/85                               | 0/85 | 0/85 |
| Result                                 | Pass                               |      |      |

|                                        |                                    |      |      |
|----------------------------------------|------------------------------------|------|------|
| Test Condition                         | +110°C / 85% RH / <b>528</b> hours |      |      |
| Required Sample Size                   | 77 each lot / 3 lots               |      |      |
| Electrical Test at +85°C (Fail / Pass) | 0/85                               | 0/85 | 0/85 |
| Result                                 | Pass                               |      |      |



# **MICROCHIP**

## **Package Qualification Report**

### **Physical Dimension (0Hr)**

|                      |                                  |
|----------------------|----------------------------------|
| Test Method          | JESD22 B100 and B108             |
| Test Criteria        | Within package diagram dimension |
| Required Sample Size | 10 units / 3 lots                |
| Result (Pass/Fail)   | Pass                             |

### **Mechanical Data (0Hr)**

### **Wire Bond Pull (WBP)**

|                      |                                 |
|----------------------|---------------------------------|
| Test Method          | Mil. Std. 883-2011              |
| Required Sample Size | 30 bonds from a min. 5 devices. |
| Result (Pass/Fail)   | Pass                            |

### **Wire Ball Shear (WBS)**

|                      |                                 |
|----------------------|---------------------------------|
| Test Method          | CDF-AEC-Q100-001                |
| Required Sample Size | 30 bonds from a min. 5 devices. |
| Result (Pass/Fail)   | Pass                            |

### **Solder Ball Shear (SBS)**

|                      |                                 |
|----------------------|---------------------------------|
| Test Method          | JESD22B117A                     |
| Required Sample Size | 30 bonds from a min. 5 devices. |
| Result (Pass/Fail)   | Pass                            |